

## **Amendments to the Specification**

Please amend paragraph [0025] as follows”

(a) [0025] Figure 2 shows a conversion from an XPAK module 112 to an optical communications adapter module 110 in accordance with one embodiment of the present invention. In one embodiment, the XPAK module 112 may be converted into the optical communications adapter module 110 by placing an optical communications board assembly such as the XPAK board assembly from the XPAK module 112 into a XENPAK-sized packaging unit. The XPAK module 112 is generally smaller than a XENPAK-sized packaging unit/casing and utilizes a different type of optical connectors. A typical XPAK module utilizes LC optical connectors 114 and 116 while a typical XENPAK module utilizes SC optical connectors 118 and 120. As discussed in further detail in reference to Figures 3-4 ~~Figures 5-6~~, the XPAK board assembly may be placed at a rear portion of the XENPAK-sized packaging unit and optical conversion cords may be utilized to reposition optical connectors of the XPAK board assembly to locations typically utilized in XENPAK-sized modules.